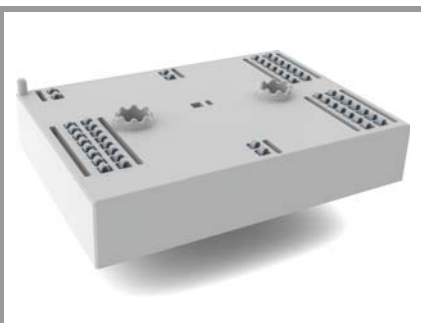


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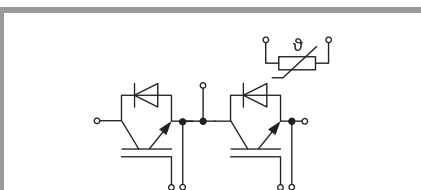
IGBT module

SKiiP 38GB12F4V19

Target Data

Features

- Fast Trench 4 IGBTs
- SiC Diodes
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

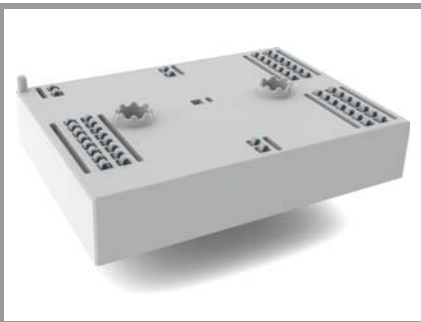


GB

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
Inverter - IGBT				
V_{CES}	$T_j = 25\text{ °C}$		1200	V
I_C	$\lambda_{paste}=0.8\text{ W/(mK)}$	$T_s = 25\text{ °C}$	303	A
		$T_j = 175\text{ °C}$	243	A
I_C	$\lambda_{paste}=2.5\text{ W/(mK)}$	$T_s = 25\text{ °C}$	361	A
		$T_j = 175\text{ °C}$	291	A
I_{Cnom}			300	A
I_{CRM}	$I_{CRM} = 3 \times I_{Cnom}$		900	A
V_{GES}			-20 ... 20	V
t_{psc}	$V_{CC} = 800\text{ V}$	$T_j = 150\text{ °C}$	10	μs
	$V_{GE} \leq 15\text{ V}$			
	$V_{CES} \leq 1200\text{ V}$			
T_j			-40 ... 175	$^{\circ}\text{C}$
Inverse - Diode				
I_F	$\lambda_{paste}=0.8\text{ W/(mK)}$	$T_s = 25\text{ °C}$	133	A
		$T_j = 175\text{ °C}$	108	A
I_F	$\lambda_{paste}=2.5\text{ W/(mK)}$	$T_s = 25\text{ °C}$	148	A
		$T_j = 175\text{ °C}$	120	A
I_{Fnom}			80	A
I_{FRM}			224	A
I_{FSM}	10 ms, sin 180°, $T_j = 150\text{ °C}$		212	A
T_j			-40 ... 175	$^{\circ}\text{C}$
Module				
$I_t(\text{RMS})$	$T_{terminal} = 80\text{ °C}$, 20 A per spring		t.b.d.	A
T_{stg}			-40 ... 125	$^{\circ}\text{C}$
V_{isol}	AC sinus 50 Hz, t = 1 min		2500	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
$V_{CE(sat)}$	$I_C = 300\text{ A}$ $V_{GE} = 15\text{ V}$ chiplevel	$T_j = 25\text{ °C}$		2.05	2.42	V
		$T_j = 150\text{ °C}$		2.59	2.96	V
V_{CE0}	chiplevel	$T_j = 25\text{ °C}$		1.10	1.28	V
		$T_j = 150\text{ °C}$		0.95	1.13	V
r_{CE}	$V_{GE} = 15\text{ V}$ chiplevel	$T_j = 25\text{ °C}$		3.2	3.8	m Ω
		$T_j = 150\text{ °C}$		5.5	6.1	m Ω
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 10.4\text{ mA}$		5.2	5.8	6.4	V
I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = 1200\text{ V}$, $T_j = 25\text{ °C}$			0.1	1.6	mA
C_{ies}	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$		17.60		nF
C_{oes}		$f = 1\text{ MHz}$		1.16		nF
C_{res}		$f = 1\text{ MHz}$		0.94		nF
Q_G	- 8 V...+ 15 V			1700		nC
R_{Gint}	$T_j = 25\text{ °C}$			0		Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$ $I_C = 300\text{ A}$	$T_j = 150\text{ °C}$				ns
t_r		$T_j = 150\text{ °C}$				ns
E_{on}				10		mJ
$t_{d(off)}$						ns
t_f						ns
E_{off}	$V_{GE} = +15/-15\text{ V}$			22		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8\text{ W/(mK)}$			0.16		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5\text{ W/(mK)}$			0.12		K/W

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MiniSKiiP® 3 Dual

IGBT module

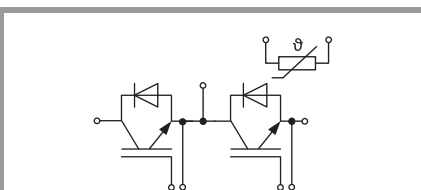
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Target Data

Features

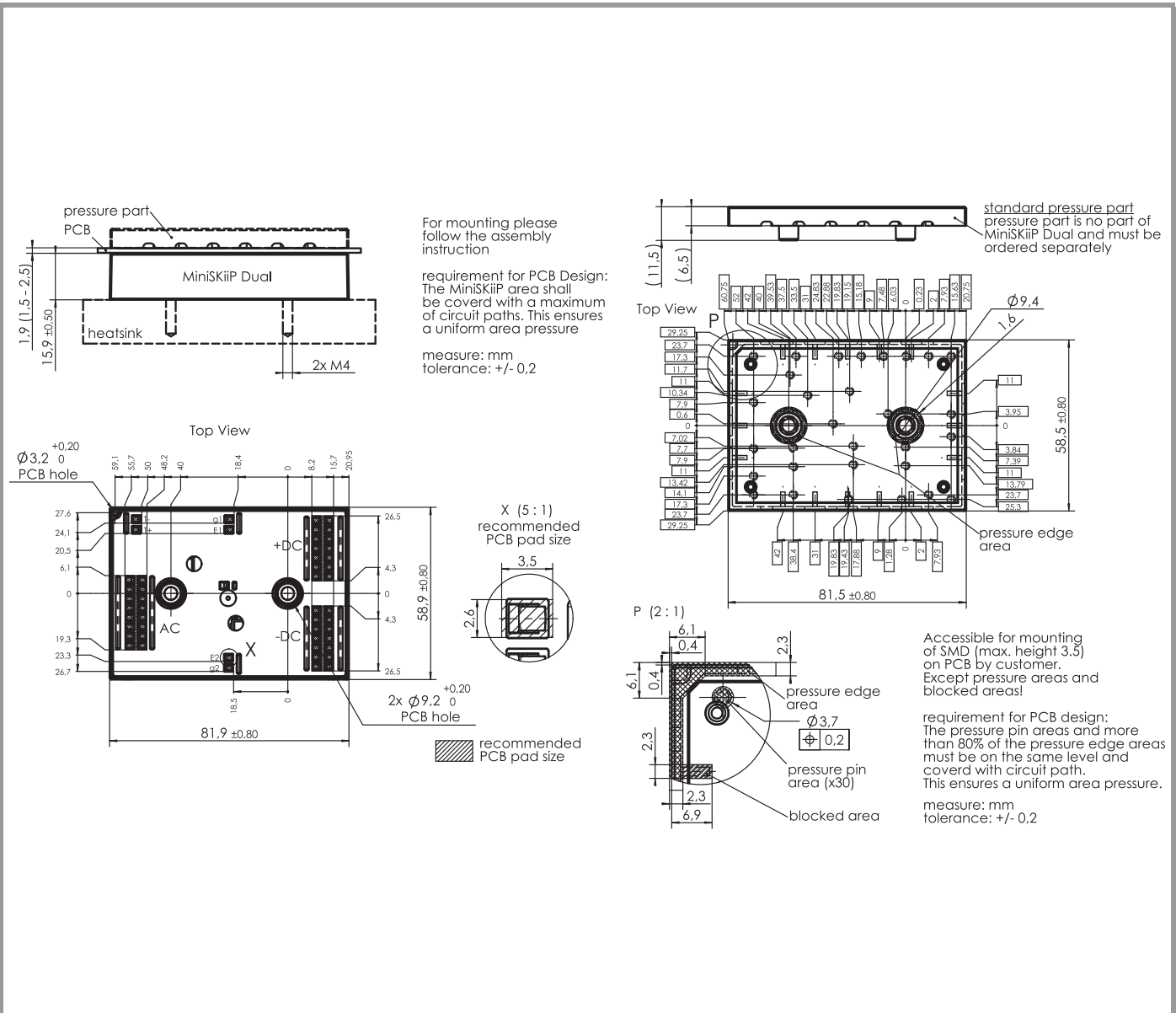
- Fast Trench 4 IGBTs
- SiC Diodes
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse - Diode						
$V_F = V_{EC}$	$I_F = 80\text{ A}$ $V_{GE} = 0\text{ V}$ chipllevel	$T_j = 25\text{ °C}$		1.40	1.60	V
		$T_j = 150\text{ °C}$		1.80	2.10	V
V_{F0}	chipllevel	$T_j = 25\text{ °C}$		0.95	1.05	V
		$T_j = 150\text{ °C}$		0.83	0.90	V
r_F	chipllevel	$T_j = 25\text{ °C}$		5.6	6.9	mΩ
		$T_j = 150\text{ °C}$		12	15	mΩ
I_{RRM}	$I_F = 80\text{ A}$	$T_j = 150\text{ °C}$		-		A
Q_{rr}	$di/dt_{off} = 500\text{ A}/\mu\text{s}$	$T_j = 150\text{ °C}$		-		μC
E_{rr}	$V_{GE} = -15\text{ V}$ $V_{CC} = 600\text{ V}$	$T_j = 150\text{ °C}$		-		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8\text{ W}/(\text{mK})$			0.36		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5\text{ W}/(\text{mK})$			0.3		K/W
Module						
L_{CE}				15		nH
M_s	to heat sink		2		2.5	Nm
W				76		g
Temperature Sensor						
R_{100}	$T_c=100\text{ °C}$ ($R_{25}=5\text{ k}\Omega$)			$493 \pm 5\%$		Ω
$B_{25/85}$	$R_{(T)}=R_{25} \cdot \exp[B_{25/85} \cdot (1/T-1/298)]$, [T]=K			3420		K

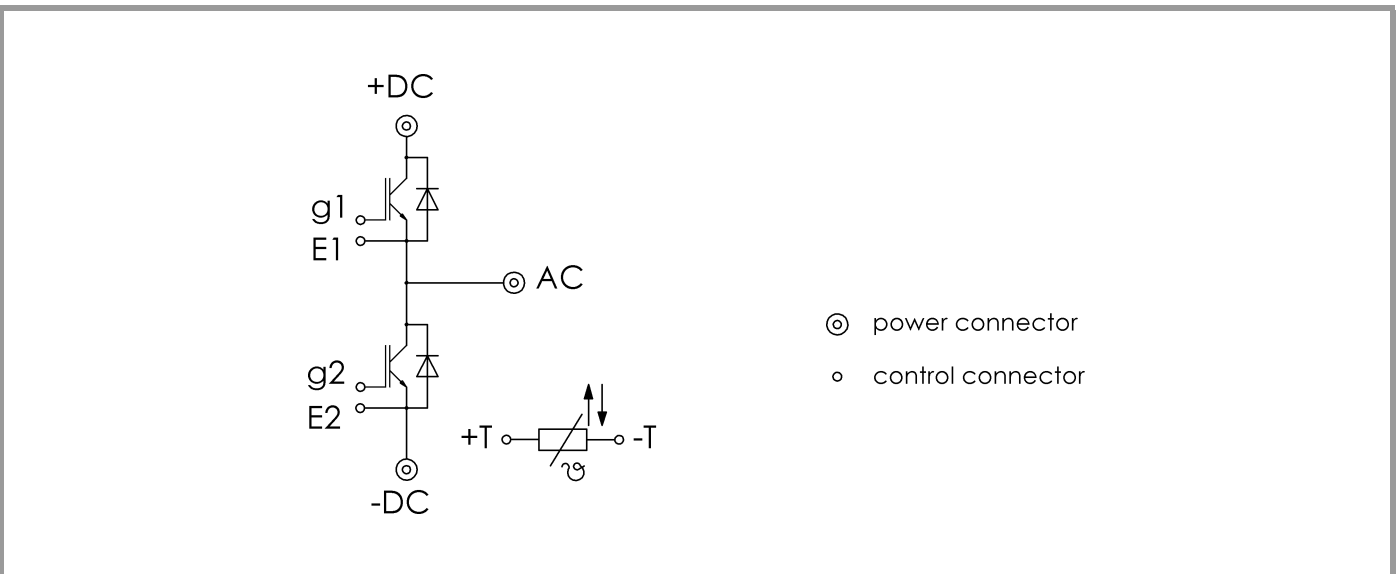


GB

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pinout, dimensions



pinout

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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